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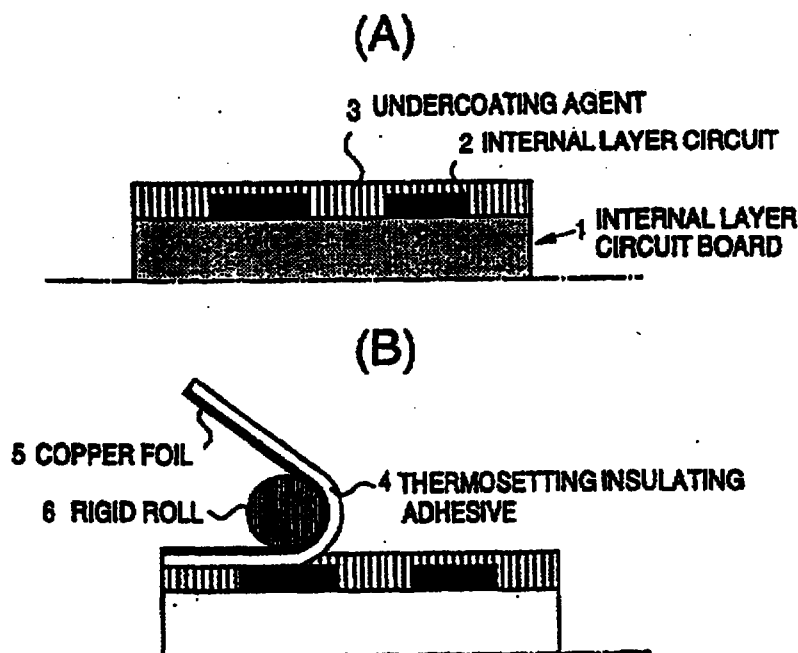
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- ☐ Description : paged to paged
- ☒ Claim(s) : paged **37** to paged **44**
- ☐ Drawing(s) : paged to paged
- ☐ Abstract : paged to paged

(54) Title: MULTILAYER PRINTED CIRCUIT BOARD AND PROCESS FOR PRODUCING THE SAME



(57) Abstract

A multilayer printed circuit board, characterized by being composed of an internal layer circuit board (1) coated with a light and heat curable undercoating agent (3), a copper foil (5) and an insulating adhesive (4) comprising as the main component a brominated bisphenol type epoxy resin or brominated phenoxy resin having a weight average molecular weight of at least 10,000, the copper foil (5) and the insulating adhesive (4) being laminated to one side or both sides of the internal layer circuit board (1) and being integrally cured with the internal layer circuit board (1) and the undercoating agent (3).